

ABSTRACT

A wafer on which semiconductor elements, a multilevel interconnect layer, a bonding pad, a passivation film, and the like are formed is coated with a buffer coat film.

- 5 Thereafter, the buffer coat film is patterned by exposure and development so that parts of the buffer coat film located on the bonding pads and scribe line regions and a part of the buffer coat film located on a periphery region of the wafer are removed, thereby forming apertures. The rear surface of the wafer is polished by polishing slurry with a surface protection tape bonded to the surface of the wafer by adhesive paste. In the periphery
- 10 region, the apertures including the scribe line regions are blocked by the adhesive paste so that polishing slurry does not permeate.